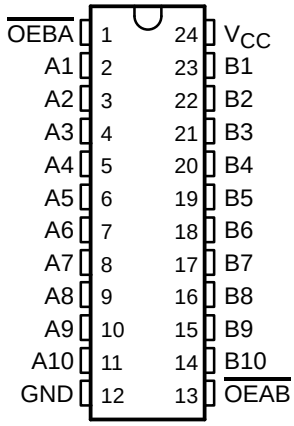
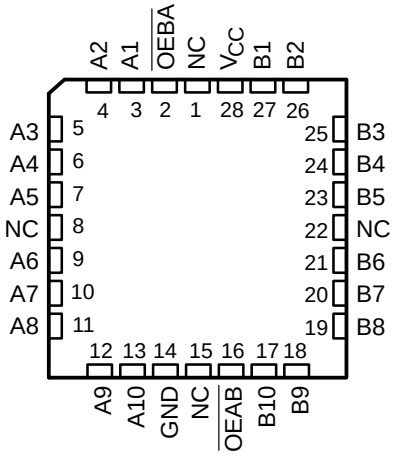
- **State-of-the-Art *EPIC*-II*B*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (SOIC) and Shrink Small-Outline (SSOP) Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs**

SN54ABT862 . . . JT PACKAGE
SN74ABT862 . . . DB, DW, OR NT PACKAGE
(TOP VIEW)



SN54ABT862 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The ′ABT862 is a 10-bit transceiver designed for asynchronous communication between data buses. The control function implementation allows for maximum flexibility in timing.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the output-enable ($\overline{OEAB}$ and $\overline{OEBA}$) inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT862 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT862 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT862 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

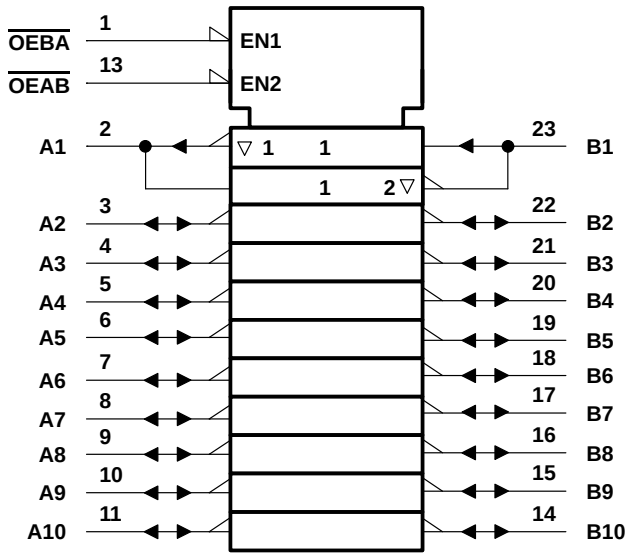
INPUTS		OPERATION
$\overline{OEAB}$	$\overline{OEBA}$	
L	H	$\overline{A}$ data to B bus
H	L	$\overline{B}$ data to A bus
H	H	Isolation
L	L	Latch A and B ($A = \overline{B}$)

PRODUCT PREVIEW

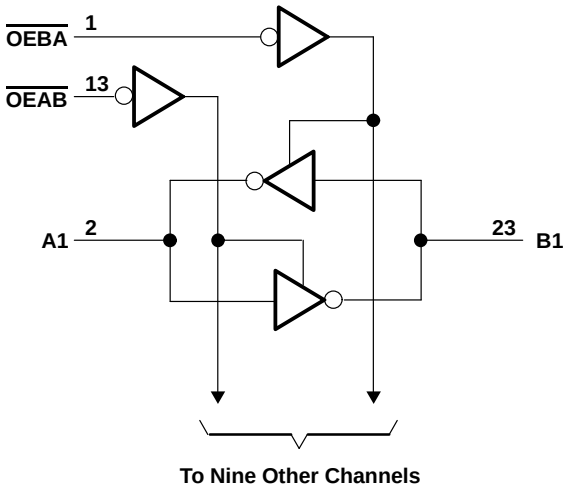
EPIC-IIB is a trademark of Texas Instruments Incorporated.

PRODUCT PREVIEW

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) . . . . . –0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O . . . . . –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT862 . . . . . 96 mA
SN74ABT862 . . . . . 128 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . –18 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . –50 mA
Maximum power dissipation at T_A = 55°C (in still air): DB package . . . . . 0.7 W
DW package . . . . . 1 W
NT package . . . . . 1.3 W
Storage temperature range . . . . . –65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			SN54ABT862		SN74ABT862		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 2: Unused or floating pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T_A = 25°C			SN54ABT862		SN74ABT862		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V,	I_{OH} = –3 mA		3			3		3		
	V_{CC} = 4.5 V,	I_{OH} = –24 mA		2			2				
	V_{CC} = 4.5 V,	I_{OH} = –32 mA		2‡					2		
V_{OL}	V_{CC} = 4.5 V,	I_{OL} = 48 mA				0.55		0.55			V
	V_{CC} = 4.5 V,	I_{OL} = 64 mA				0.55‡				0.55	
I_I	V_{CC} = 5.5 V, V_I = V_{CC} or GND		Control inputs			±1		±1		±1	µA
			A or B ports			±100		±100		±100	
I_{OZH}§	V_{CC} = 5.5 V,	V_O = 2.7 V				50		50		50	µA
I_{OZL}§	V_{CC} = 5.5 V,	V_O = 0.5 V				–50		–50		–50	µA
I_{off}	V_{CC} = 0,	V_I or $V_O \le$ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V,	V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶	V_{CC} = 5.5 V,	V_O = 2.5 V		–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	A or B ports	Outputs high		1	250		250		250	µA
			Outputs low		24	30		30		30	mA
			Outputs disabled		0.5	250		250		250	µA
ΔI_{CC}#	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Data inputs	Outputs enabled			1.5		1.5		1.5	mA
			Outputs disabled			0.05		0.05		0.05	
		Control inputs				1.5		1.5		1.5	
C_i	V_I = 2.5 V or 0.5 V		Control inputs		4						pF
C_{io}	V_O = 2.5 V or 0.5 V		A or B ports		7						pF

† All typical values are at V_{CC} = 5 V.
‡ On products compliant to MIL-STD-883, Class B, this parameter does not apply.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PRODUCT PREVIEW

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